IN THE CLAIMS

Please amend claims 28, 30, and 37-39 as indicated below.

1-27 (Canceled)

28. (Currently Amended) An apparatus comprising:

a first integrated circuit;

a second integrated circuit residing on top of the first integrated circuit;

a first insulated bond wire connecting the first integrated circuit to the second integrated circuit;

a second insulated bond wire connecting the first integrated circuit to the second integrated circuit, an outer surface of a body of at least one of the first and second insulated bond wires contacting an edge of the second integrated circuit without shorting.

29. (Previously Presented) The apparatus of claim 28, wherein the first insulated bond wire crosses over the second insulated bond wire.

30. (Currently Amended) The apparatus of claim 28, wherein a portion of insulation material at an end of the first insulated bond wire is removed when the end of the first insulated bond wire is attached to a bond pad of one of the first and second integrated circuits, and wherein a length of the removed portion is up to approximately 20 microns. ~~an outer surface of an insulation layer of the first insulated bond wire contacts the second integrated circuit~~.

31. (Previously Presented) The apparatus of claim 30, wherein the first insulated bond wire has a tight bond wire pitch angle.

32. (Previously Presented) The apparatus of claim 28, wherein insulation of each of the first and second insulated bond wires comprises polymer.

33. (Previously Presented) The apparatus of claim 28, wherein insulation of each of the first and second insulated bond wires is selected from the group consisting of polyvinyl, polytetrafluoroethylene, fluorinated ethylene propylene, and polyimide.

34. (Previously Presented) The apparatus of claim 28, wherein each of the first and second insulated bond wires is comprised of a metal selected from the group consisting of gold, silver, aluminum, and copper.

35. (Previously Presented) The apparatus of claim 28, wherein the first integrated circuit, the second integrated circuit, the first insulated bond wire, and the second insulated bond wire reside within a plastic mold.

36. (Previously Presented) The apparatus of claim 28, wherein an outer surface of an insulation layer of the first insulated bond wire contacts an outer surface of an insulation layer of the second insulated bond wire.

37. (Currently Amended) The apparatus of claim 28, wherein the first and second integrated circuits include bond pads, wherein a portion of insulation material at an end of the second

insulated bond wire is removed when the end of the second insulated bond wire is attached to one of the bond pads, and wherein a length of the removed portion is up to approximately 5 percent of a total length of the second insulated bond wire.

38. (Currently Amended) The apparatus of claim 28, further comprising: ~~a substrate.~~

a substrate residing at a bottom of the first integrated circuit;

a third insulated bond wire connecting the first integrated circuit to the substrate; and

a fourth insulated bond wire connecting the second integrated circuit to the substrate, the fourth insulated bond wire crossing over at least one of the first, second, and third insulated bond wires.

39. (Currently Amended) An integrated circuit assembly comprising a plurality of stacked integrated circuits electrically coupled by a plurality of bond wires, wherein each bond wire has an insulating material coating the bond wire, and wherein a body of at least one of the bond wires contacts an edge of at least one of the integrated circuits without shorting.

40. (Previously Presented) The integrated circuit assembly of claim 39, wherein the insulating material has a thickness in a range of approximately 0.2 micrometers to 0.6 micrometers.

41. (Previously Presented) The integrated circuit assembly of claim 39, wherein the insulating material comprises a polymer.

42. (Previously Presented) The integrated circuit assembly of claim 39, wherein the plurality of bond wires includes bond wires that cross over each other.

43. (Currently Amended) The integrated circuit assembly of claim 39, wherein the plurality of bond wires includes bond wires that have insulating material that is thick enough such that the edge of the at least one integrated circuit does not cut into the insulating material of the bond wires ~~touches at least one of the plurality of stacked integrated circuits~~.

44. (Previously Presented) The integrated circuit assembly of claim 39, further comprising a substrate.

45. (Previously Presented) An apparatus comprising:

a first integrated circuit;

a second integrated circuit residing on top of the first integrated circuit;

an insulated bond wire connecting the first integrated circuit to the second integrated circuit;

an uninsulated bond wire connecting the first integrated circuit to the second integrated circuit.

46. (Previously Presented) The apparatus of claim 45, wherein the insulated bond wire crosses over the uninsulated bond wire.

47. (Previously Presented) The apparatus of claim 45, wherein the uninsulated bond wire touches an outer surface of insulating material of the insulated bond wire.